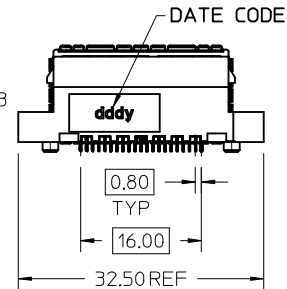
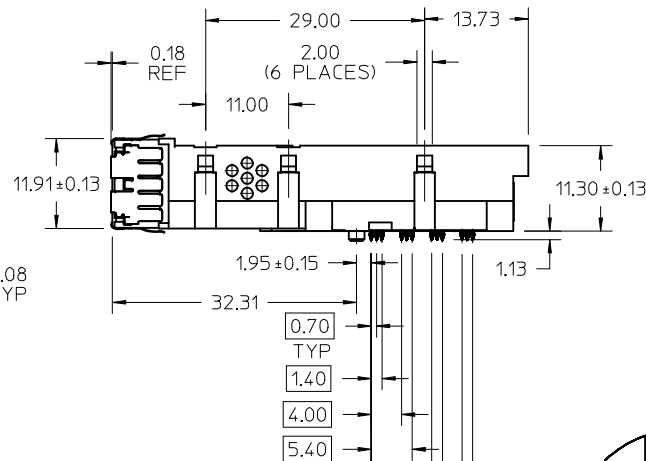
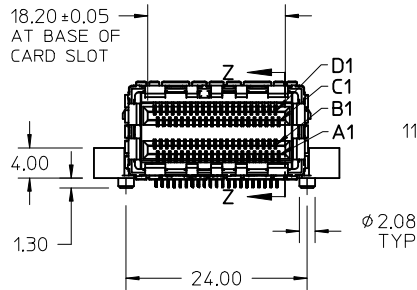
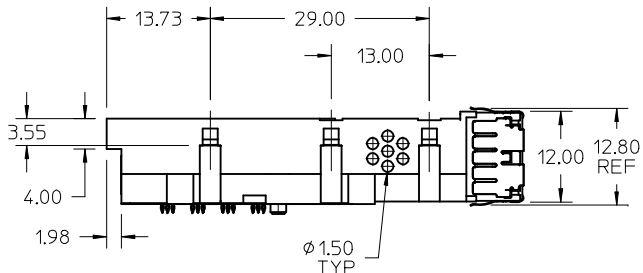
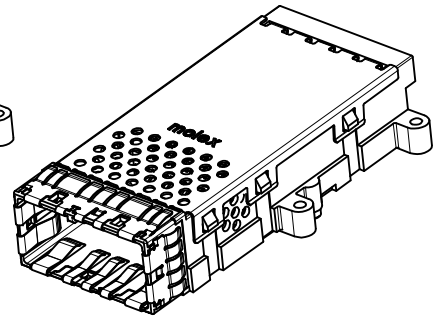
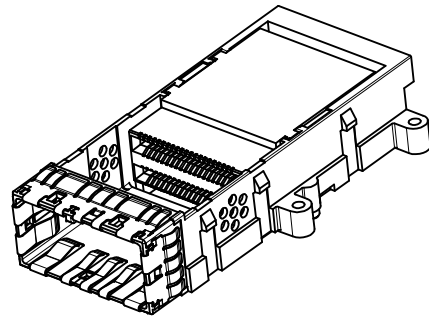
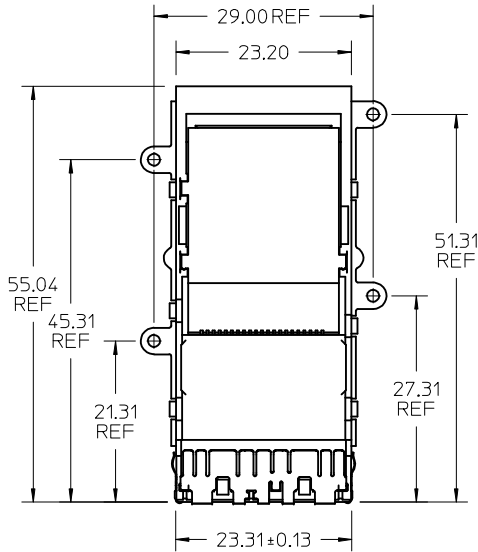
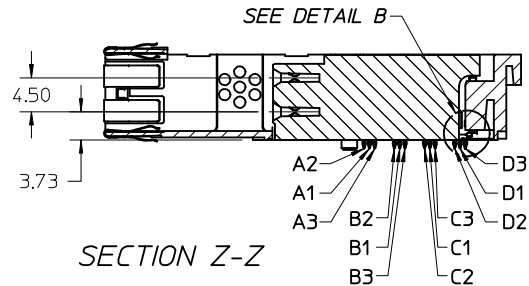
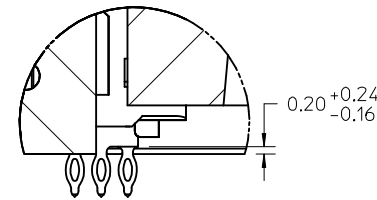


MATERIAL	DESCRIPTION
1705010001	NO COVER
1705011001	WITH COVER

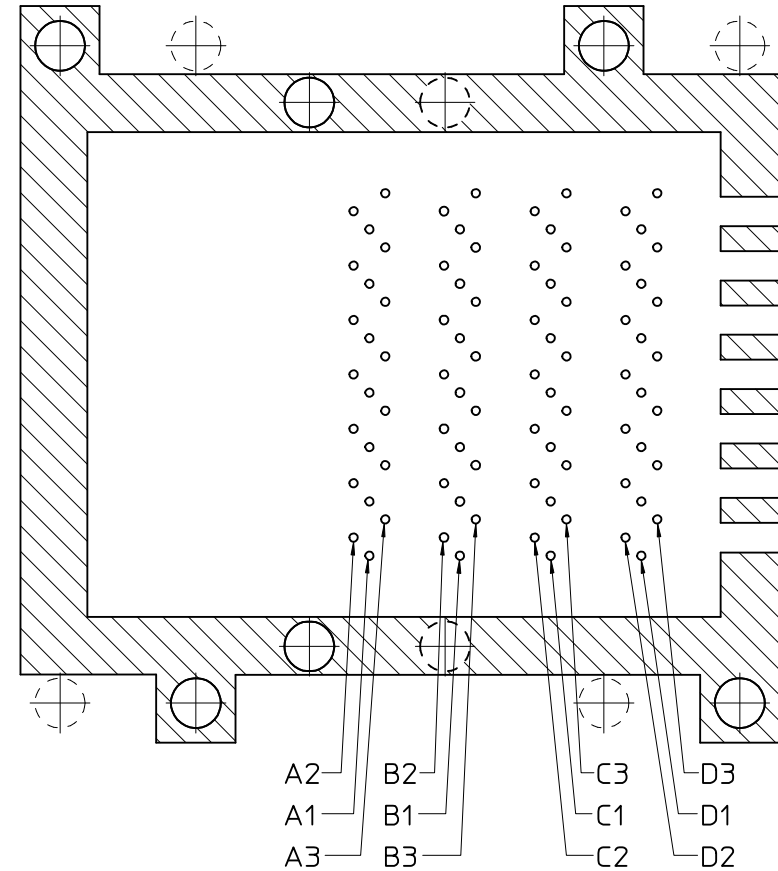
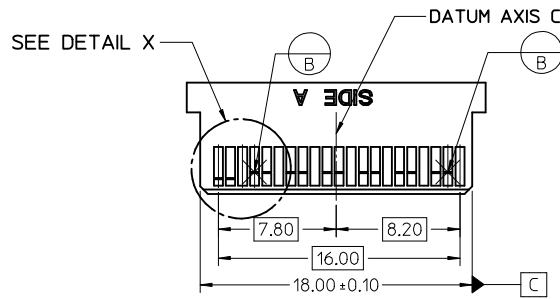
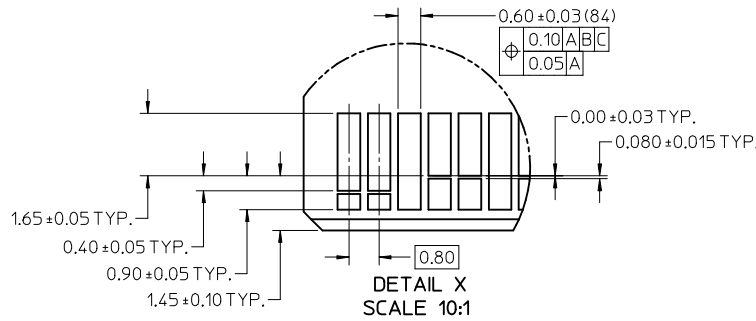
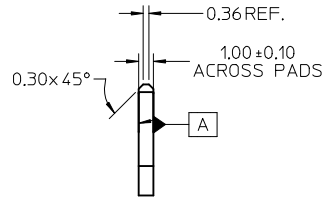
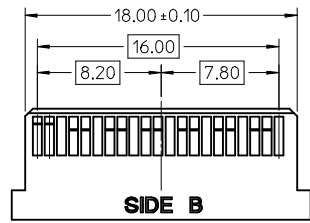


- NOTES:
- MATERIALS:
CONNECTOR HOUSING: HIGH TEMPERATURE THERMOPLASTIC GLASS-FILLED, UL 94V-0
EMI HOUSING: NICKEL PLATED DIE CAST ALLOY
COVER: STAINLESS STEEL
EMI CLIPS: NICKEL PLATED PHOS BRONZE
TERMINALS: COPPER ALLOY
 - PLATING:
CONTACT AREA: 0.764mm MIN. GOLD OVER 2.544mm MIN. NICKEL
TAIL AREA: 0.764mm - 1.524mm TIN OVER 1.274mm MIN NICKEL
 - THIS CONNECTOR IS DESIGNED TO MATE WITH MOLEX CABLE SERIES INDICATED IN THE MOLEX PRODUCT SPEC. PS-170465-0001.
 - REFER TO ROUTING GUIDE AS-170501-0002 FOR PCB TRACE INFORMATION.
 - PACKAGING SPECIFICATION: TRAY PACK PER PK-170501-0001.
 - REFER TO AS-170501-0001 FOR THE APPLICATION SPECIFICATION.
 - MOUNTING HARDWARE REQUIRED: M2x0.4 CAP SCREWS (6)
MOUNTING SCREW LENGTH: BOARD THICKNESS + 4mm MAX
 - THERMAL SOLUTION MUST PROVIDE MODULE GUIDANCE OR MODULE MAY STUB ON CONNECTOR DURING MATING.
SAME FUNCTION AS COVER OR HEATSINK.



DETAIL B
SCALE 10:1

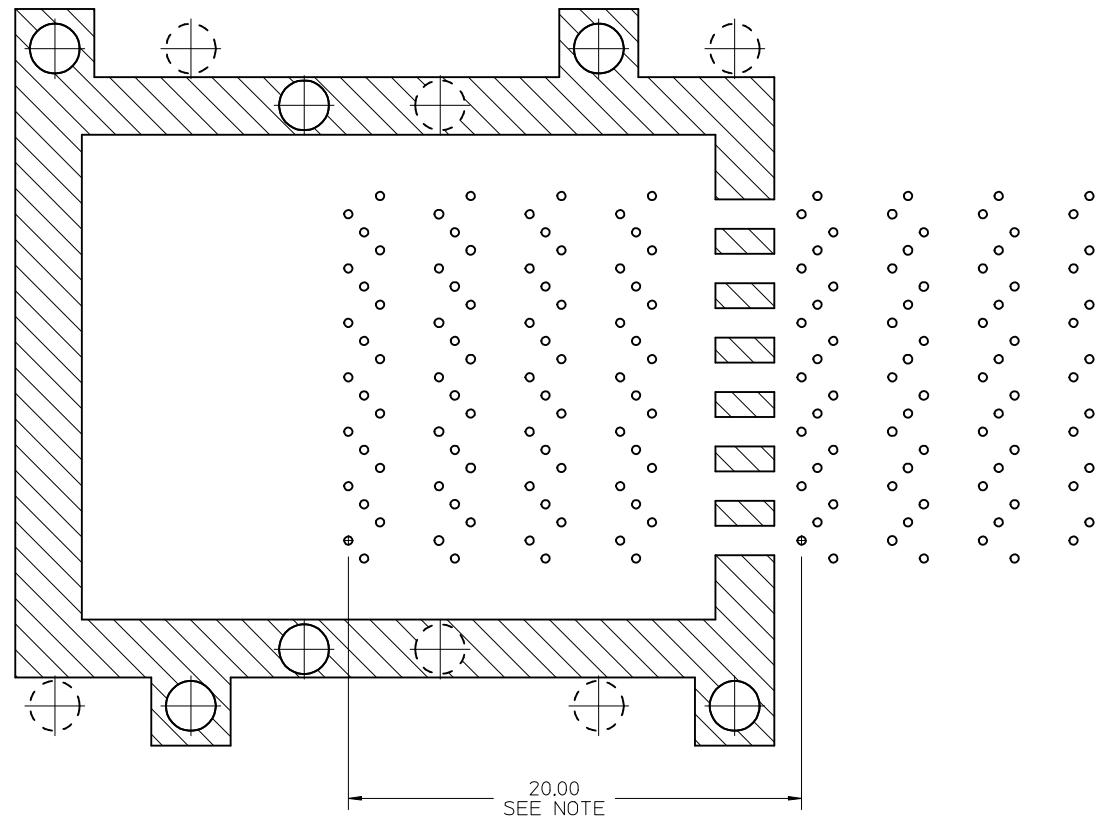
ADD TOL., CUT-OUT EC NO: UCP2013-2408 2012/12/12 DRWNG:GPRAIT CHKD:MBANAKIS 2012/12/12 APPR:MBANAKIS 2012/12/18	DESCRIPTION REV D1	QUALITY SYMBOLS ▽=0 ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 2:1	DESIGN UNITS METRIC	 THIRD ANGLE PROJECTION	
				mm	INCH	DRAWN BY JLONG	DATE 2010/05/20	TITLE I-PASS PLUS CXP EXTENDED 84 CIRCUIT, 0.8MM I/O		
			4 PLACES	± ---	± ---	CHECKED BY JLONG	DATE 2010/05/20			
			3 PLACES	± ---	± ---	APPROVED BY MBANAKIS	DATE 2012/12/18			
			2 PLACES	± 0.25	± ---	MATERIAL NO.	DOCUMENT NO.			
			1 PLACE	± ---	± ---	SEE CHART				SHEET NO. 1 OF 5
			ANGULAR ±1/2°		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SD-170501-0001			
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION										



NOTES:

- 0.03 MINIMUM KEEP OUT FOR SOLDER MASK AROUND ALL PADS
- DATUM B TARGETS ARE DEFINED BY THE RESPECTIVE PAD CENTER LINES AND THE LEADING EDGE OF THE TARGET PADS

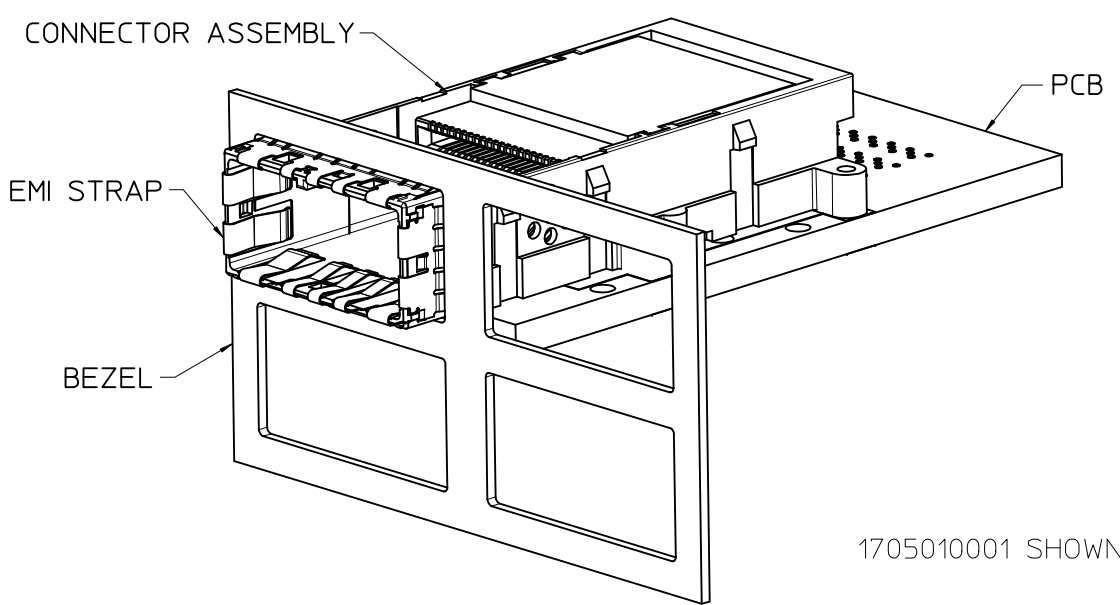
SEE SHEET 1 EC NO: UCP2013-2408 DRAWN: GPRATT CHKD: MBANAKIS APPR: MBANAKIS D1	REV	DESCRIPTION 2012/12/12 2012/12/12 2012/12/18	QUALITY SYMBOLS ▽=0 ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 6:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	TITLE I-PASS PLUS CXP EXTENDED 84 CIRCUIT, 0.8MM I/O MOLEX MOLEX INCORPORATED SD-170501-0001 THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		
					mm	INCH	DRAWN BY JLONG	DATE 2010/05/20	MATERIAL NO. 1705010001			DOCUMENT NO. SD-170501-0001	SHEET NO. 3 OF 5
				4 PLACES ± --- ± ---		CHECKED BY JLONG		DATE 2010/05/20					
				3 PLACES ± --- ± ---		APPROVED BY MBANAKIS		DATE 2012/12/18					
				2 PLACES ± 0.25 ± ---		ANGULAR ±1/2°							
				1 PLACE ± --- ± ---		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS							



NOTE:

1. WHEN USED WITH CONNECTOR SERIES 170502
VIA PATTERN WILL APPEAR AS SHOWN.

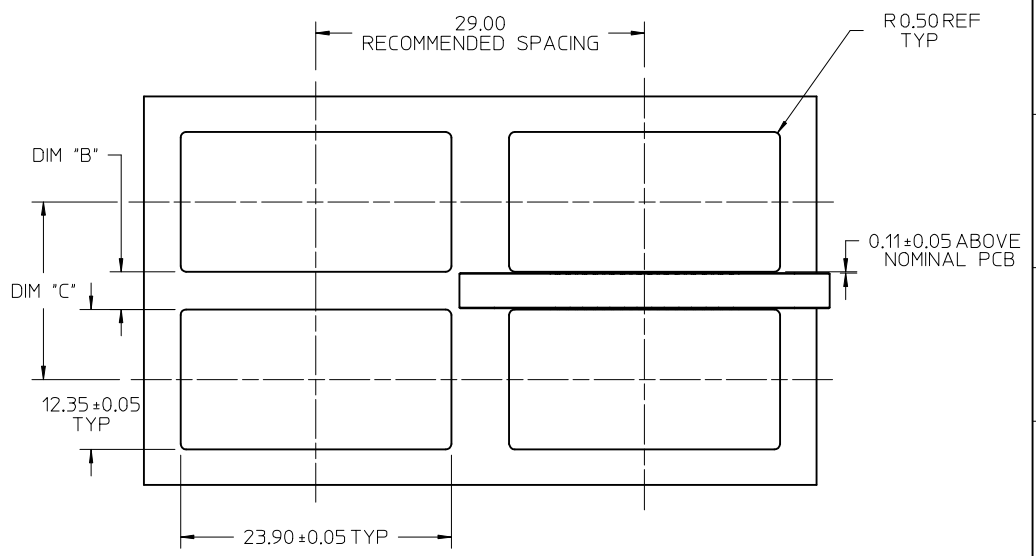
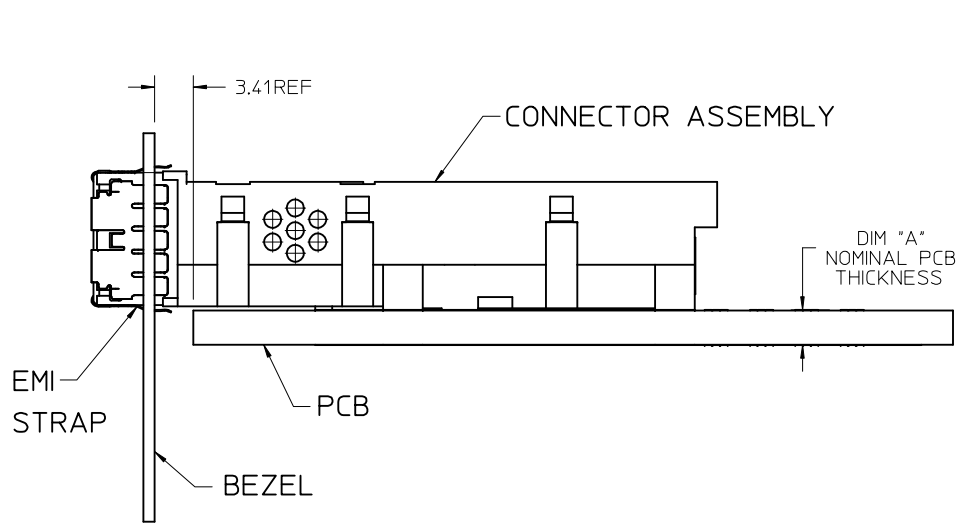
SEE SHEET 1 EC NO: UCP2013-2408 2012/12/12 DRAWING PRATT CHKD: MBANAKIS 2012/12/12 APPR: MBANAKIS 2012/12/18	DESCRIPTION	QUALITY SYMBOLS ▽=0 ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 6:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
				mm	INCH	DRAWN BY JLONG	DATE 2010/05/20	TITLE I-PASS PLUS CXP EXTENDED 84 CIRCUIT, 0.8MM I/O		
			4 PLACES	± ---	± ---	CHECKED BY JLONG	DATE 2010/05/20			
			3 PLACES	± ---	± ---	APPROVED BY MBANAKIS	DATE 2012/12/18			
			2 PLACES	± 0.25	± ---	MATERIAL NO. 1705010001	DOCUMENT NO. SD-170501-0001			
			1 PLACE	± ---	± ---	SIZE C	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			
			ANGULAR ±1/2°		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MOLEX MOLEX INCORPORATED			SHEET NO. 4 OF 5



DIM "A"	DIM "B"	DIM "C"	MINIMUM PCB
3.10	3.32	15.67	10% NOM THK
1.60	1.82	14.17	1.44
2.80	3.02	15.37	10% NOM THK

NOTE: WITH 1.44 MINIMUM PCB THICKNESS, WILL NOT SUPPORT PLUGS WITH GREATER THAN 28 AWG CABLE.

1705010001 SHOWN



SEE SHEET 1 EC NO: UCP2013-2408 2012/12/12 DRWNG: GRATT CHKD: MBANAKIS 2012/12/12 APPR: MBANAKIS 2012/12/18	REV D1	DESCRIPTION	QUALITY SYMBOLS ▽=0 ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED) mm INCH 4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.25 ± --- 1 PLACE ± --- ± --- ANGULAR ± 1/2° DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		DIMENSION STYLE MM ONLY DRAWN BY DATE JLONG 2010/05/20 CHECKED BY DATE JLONG 2010/05/20 APPROVED BY DATE MBANAKIS 2012/12/18 MATERIAL NO. 1705010001 SIZE C		SCALE 3:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION I-PASS PLUS CXP EXTENDED 84 CIRCUIT, 0.8MM I/O MOLEX MOLEX INCORPORATED DOCUMENT NO. SD-170501-0001 SHEET NO. 5 OF 5
								TITLE		